

# N-Channel 20 V (D-S) MOSFET



#### Marking code: J

PRODUCT SUMMARY					
V <sub>DS</sub> (V)	20				
$R_{DS(on)}$ max. ( $\Omega$ ) at $V_{GS} = 4.5 \text{ V}$	0.420				
$R_{DS(on)}$ max. ( $\Omega$ ) at $V_{GS} = 2.5 \text{ V}$	0.492				
$R_{DS(on)}$ max. ( $\Omega$ ) at $V_{GS}$ = 1.8 V	0.597				
$R_{DS(on)}$ max. ( $\Omega$ ) at $V_{GS} = 1.5 \text{ V}$	0.762				
Q <sub>g</sub> typ. (nC)	1				
I <sub>D</sub> (A)	0.53				
Configuration	Single				

#### **FEATURES**

- TrenchFET® power MOSFET
- Gate-source ESD protected: 1000 V
- Material categorization: for definitions of compliance please see www.vishav.com/doc?99912

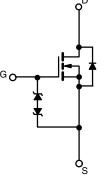


HALOGEN

FREE

#### **APPLICATIONS**

- Load / power switching for portable devices
- Drivers: relays, solenoids, lamps, hammers, displays, memories
- Battery operated systems
- Power supply converter circuits



N-Channel MOSFET

ORDERING INFORMATION	
Package	SC-89
Lead (Pb)-free and halogen-free	Si1062X-T1-GE3

PARAMETER		SYMBOL	LIMIT	UNIT
Drain-source voltage		V <sub>DS</sub>	20	v
Gate-source voltage		V <sub>GS</sub>	± 8	
Continuous drain current (T <sub>J</sub> = 150 °C) <sup>a</sup>	T <sub>A</sub> = 25 °C		0.53 <sup>a, b</sup>	A
	T <sub>A</sub> = 70 °C	l <sub>D</sub>	0.43 <sup>a, b</sup>	
Pulsed drain current (t = 300 μs)		I <sub>DM</sub>	2	A
Continuous source-drain diode current	T <sub>A</sub> = 25 °C	Is	0.18 <sup>a, b</sup>	$\neg$
Martin and distribution 2	T <sub>A</sub> = 25 °C	D	0.22 <sup>a, b</sup>	W
Maximum power dissipation <sup>a</sup>	T <sub>A</sub> = 70 °C	P <sub>D</sub>	0.14 <sup>a, b</sup>	
Operating junction and storage temperature range		T <sub>J</sub> , T <sub>stq</sub>	-55 to +150	°C

THERMAL RESISTANCE RATINGS						
PARAMETER	SYMBOL	TYP.	MAX.	UNIT		
Maximum junction to ambient b	t ≤ 5 s	$R_{thJA}$	440	530	°C/W	
Maximum junction-to-ambient <sup>b</sup>	Steady state		540	650	C/VV	

#### Notes

a. Surface mounted on 1" x 1" FR4 board

b. t = 5 s



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PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT	
Static				•			
Drain-source breakdown voltage	V <sub>DS</sub>	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$	20	-	-	V	
V <sub>DS</sub> temperature coefficient	$\Delta V_{DS}/T_{J}$	J 050 A	-	11	-		
V <sub>GS(th)</sub> temperature coefficient	$\Delta V_{GS(th)}/T_J$	I <sub>D</sub> = 250 μA	-	-1.8	-	mV/°C	
Gate-source threshold voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	0.4	-	1	V	
Gate-source leakage		$V_{DS} = 0 \text{ V}, V_{GS} = \pm 8 \text{ V}$	-	-	± 30	-	
Gate-source leakage	I <sub>GSS</sub>	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 4.5 \text{ V}$	-	-	± 1		
Zero gate voltage drain current	lana	$V_{DS} = 20 \text{ V}, V_{GS} = 0 \text{ V}$	-	-	1	μA	
Zero gate voltage drain current	I <sub>DSS</sub>	$V_{DS} = 20 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 85 ^{\circ}\text{C}$	-	-	10	1	
On-state drain current <sup>a</sup>	I <sub>D(on)</sub>	$V_{DS} = \ge 5 \text{ V}, V_{GS} = 4.5 \text{ V}$	2	-	1	Α	
		$V_{GS} = 4.5 \text{ V}, I_D = 0.5 \text{ A}$	-	0.350	0.420	Ω	
Drain-source on-state resistance a	D	$V_{GS} = 2.5 \text{ V}, I_D = 0.2 \text{ A}$	-	0.410	0.492		
Drain-source on-state resistance 4	R <sub>DS(on)</sub>	$V_{GS} = 1.8 \text{ V}, I_D = 0.2 \text{ A}$	-	0.459	0.597		
		$V_{GS} = 1.5 \text{ V}, I_D = 0.05 \text{ A}$	-	0.510	0.762		
Forward transconductance	9fs	$V_{DS} = 10 \text{ V}, I_D = 0.5 \text{ A}$	-	7.5	-	S	
Dynamic <sup>b</sup>							
Input capacitance	C <sub>iss</sub>		-	43	ı	pF	
Output capacitance	C <sub>oss</sub>	$V_{DS} = 10 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$	-	14	-		
Reverse transfer capacitance	C <sub>rss</sub>		-	8	ı		
Total gata charge		$V_{DS} = 10 \text{ V}, V_{GS} = 8 \text{ V}, I_{D} = 0.5 \text{ A}$	-	1.8	2.7		
Total gate charge	Qg		-	1	2	nC	
Gate-source charge	Q <sub>gs</sub>	$V_{DS} = 10 \text{ V}, V_{GS} = 4.5 \text{ V}, I_{D} = 0.5 \text{ A}$	-	0.16	-	- nc	
Gate-drain charge	$Q_{gd}$		-	0.13	-		
Gate resistance	R <sub>g</sub>	f = 1 MHz	-	12.2	-	Ω	
Turn-on delay time	t <sub>d(on)</sub>		-	2	4		
Rise time	t <sub>r</sub>	$V_{DD} = 10 \text{ V}, R_{L} = 20 \Omega,$	-	14	24	ns	
Turn-off delay time	t <sub>d(off)</sub>	$I_D \cong 0.4 \text{ A}, V_{GEN} = 4.5 \text{ V}, R_g = 1 \Omega$	-	16	30		
Fall time	t <sub>f</sub>		-	11	20		
<b>Drain-Source Body Diode Characteris</b>	stics						
Pulse diode forward current <sup>a</sup>	I <sub>SM</sub>		-	-	2	Α	
Body diode voltage	V <sub>SD</sub>	I <sub>S</sub> = 0.4 A	-	0.8	1.2	V	
Body diode reverse recovery time	t <sub>rr</sub>		-	10	15	ns	
Body diode reverse recovery charge	Q <sub>rr</sub>	1 = 0.4 A di/d+ 400 A/:	-	2	4	nC	
Reverse recovery fall time	ta	I <sub>F</sub> = 0.4 A, di/dt = 100 A/μs	-	5	-	r	
Reverse recovery rise time	t <sub>b</sub>		-	5	-	ns	

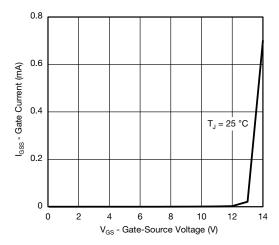
#### Notes

- a. Pulse test; pulse width  $\leq 300~\mu s,$  duty cycle  $\leq 2~\%$
- b. Guaranteed by design, not subject to production testing

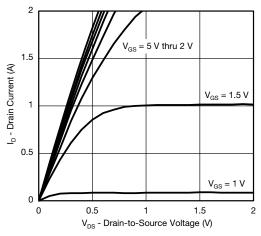
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



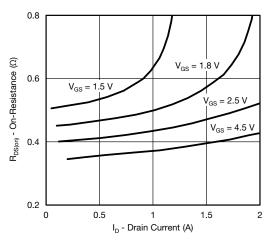
## TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



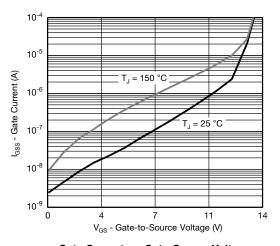
Gate Current vs. Gate-Source Voltage



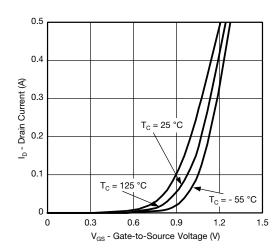
**Output Characteristics** 



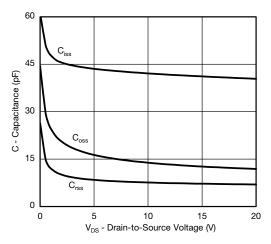
On-Resistance vs. Drain Current



Gate Current vs. Gate-Source Voltage



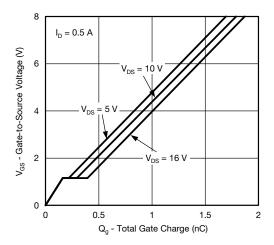
**Transfer Characteristics** 



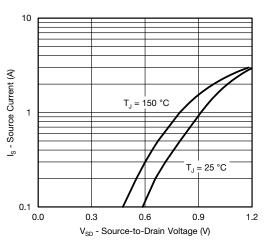
Capacitance



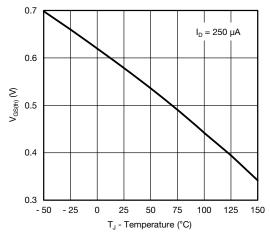
## TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



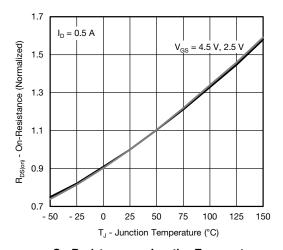
#### **Gate Charge**



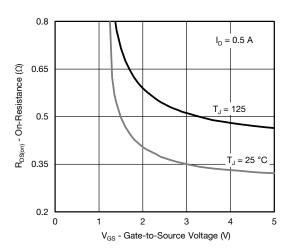
Source-Drain Diode Forward Voltage



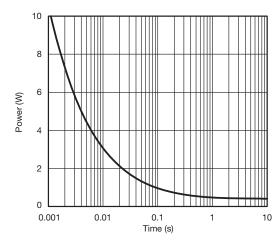
Threshold Voltage



On-Resistance vs. Junction Temperature



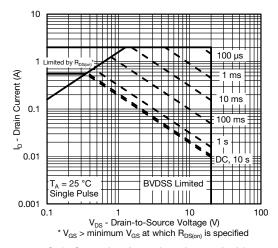
On-Resistance vs. Gate-to-Source Voltage



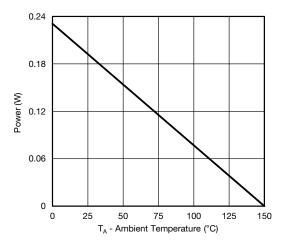
Single Pulse Power, Junction-to-Ambient



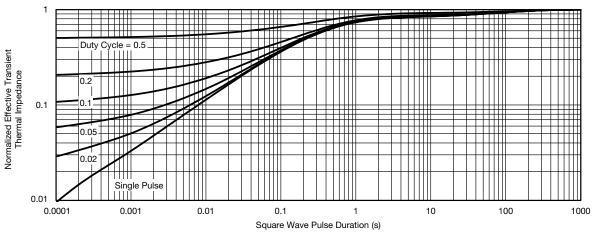
## TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



Safe Operating Area, Junction-to-Ambient



Power Derating, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Ambient

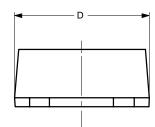
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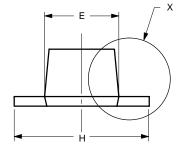


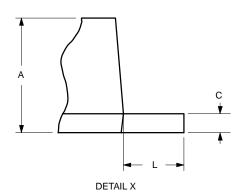


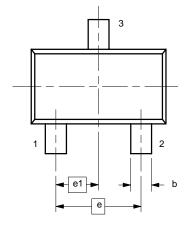
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## SC89-3





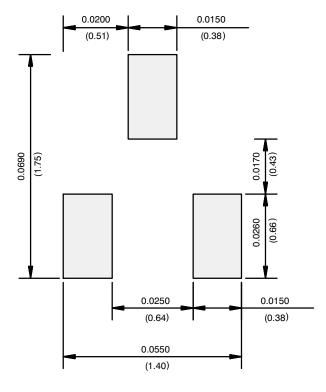




	MILLIM	IETERS	INC	HES	
Dim	Min	Max	Min	Max	
Α	0.60	0.80	0.024	0.031	
b	0.23	0.33	0.009	0.013	
С	0.10	0.20	0.004	0.008	
D	1.50	1.70	0.059	0.067	
Е	0.75	0.95	0.030	0.037	
е	1.00 BSC		0.040 BSC		
e <sub>1</sub>	0.50 BSC		0.020	BSC	
Н	1.50	1.70	0.059	0.067	
L	0.30	0.50	0.012	0.020	
ECN: S-03946—Rev. B, 09-Jul-01 DWG: 5869					



#### **RECOMMENDED MINIMUM PADS FOR SC-89: 3-Lead**



Recommended Minimum Pads Dimensions in Inches/(mm)

Return to Index

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